

SMD ■ Top View LEDs 50-615TZUMRBC/T2834N489E-T



Features

- Top View White LEDs
 - Wide viewing angle
 - Soldering methods: IR reflow soldering
 - Pb-free
 - ESD protection
 - The product itself will remain within RoHS compliant version.
 - Compliance with EU REACH.
 - Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).
- Qualification according to AEC-Q101 rev C.

Description

Due to the package design, 50-615TZ has wide viewing angle, low power consumption and white LEDs are devices which are materialized by combing blue chips and special phosphor. This feature makes the LED ideal for light guide application.

Applications

- Backlight for LCD Monitor/TV
- Light pipe application
- Indicator and backlight in office and family equipment
- General use

Device Selection Guide

| Chip Materials | Emitted Color | Resin Color |
|----------------|---------------|-------------|
| InGaN | White | Water Clear |

Absolute Ratings (T_{Soldering}=25°C)

| Parameter | Sym bol | Rating | Unit |
|--|--------------------|---|------|
| Reverse Voltage ^{*1} | V _R | 5 | V |
| Forward Current ^{*1} | I _F | F20 | mA |
| Peak Forward Current (Duty 1/10 @10ms) ^{*1} | I _{FP} | 240 | mA |
| Thermal Resistance Junction/solder point | R _{thj-s} | 20 | °C/W |
| Operating Temperature | T _{opr} | -40 ~ +100 | °C |
| Storage Temperature | T _{stg} | -40 ~ +100 | °C |
| Junction temperature | T _j | ≤ 115 | °C |
| Soldering Temperature | T _{sol} | Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec. | |

Notes:

1. For each die.
2. The products are sensitive to static electricity and must be carefully taken when handling products.

Electro-Optical Characteristics (T_a=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|-----------------|-------------------|-------|-------|-------|------|-----------------------|
| Luminous Flux | Φ | 28 | ----- | 34 | lm | I _F =120mA |
| Viewing Angle | 2θ _{1/2} | ----- | 120 | ----- | deg | I _F =120mA |
| Forward Voltage | V _F | 2.8 | ----- | 3.4 | V | I _F =120mA |

Note:

1. Tolerance of Luminous flux: ±7%.
2. Tolerance of Forward Voltage: ±0.05V.

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Bin Range of Luminous Flux

| Bin Code | Min. | Max. | Unit | Condition |
|----------|------|------|------|-----------------------|
| T28 | 28 | 30 | lm | I _F =120mA |
| T30 | 30 | 32 | | |
| T32 | 32 | 34 | | |
| T34 | 34 | 36 | | |

Note:

Tolerance of Luminous flux: ±7%.

Bin Range of Forward Voltage

| Bin Code | Min. | Max. | Unit | Condition |
|----------|------|------|------|-----------------------|
| 9 | 2.8 | 2.9 | V | I _F =120mA |
| A | 2.9 | 3.0 | | |
| B | 3.0 | 3.1 | | |
| C | 3.1 | 3.2 | | |
| D | 3.2 | 3.3 | | |
| E | 3.3 | 3.4 | | |

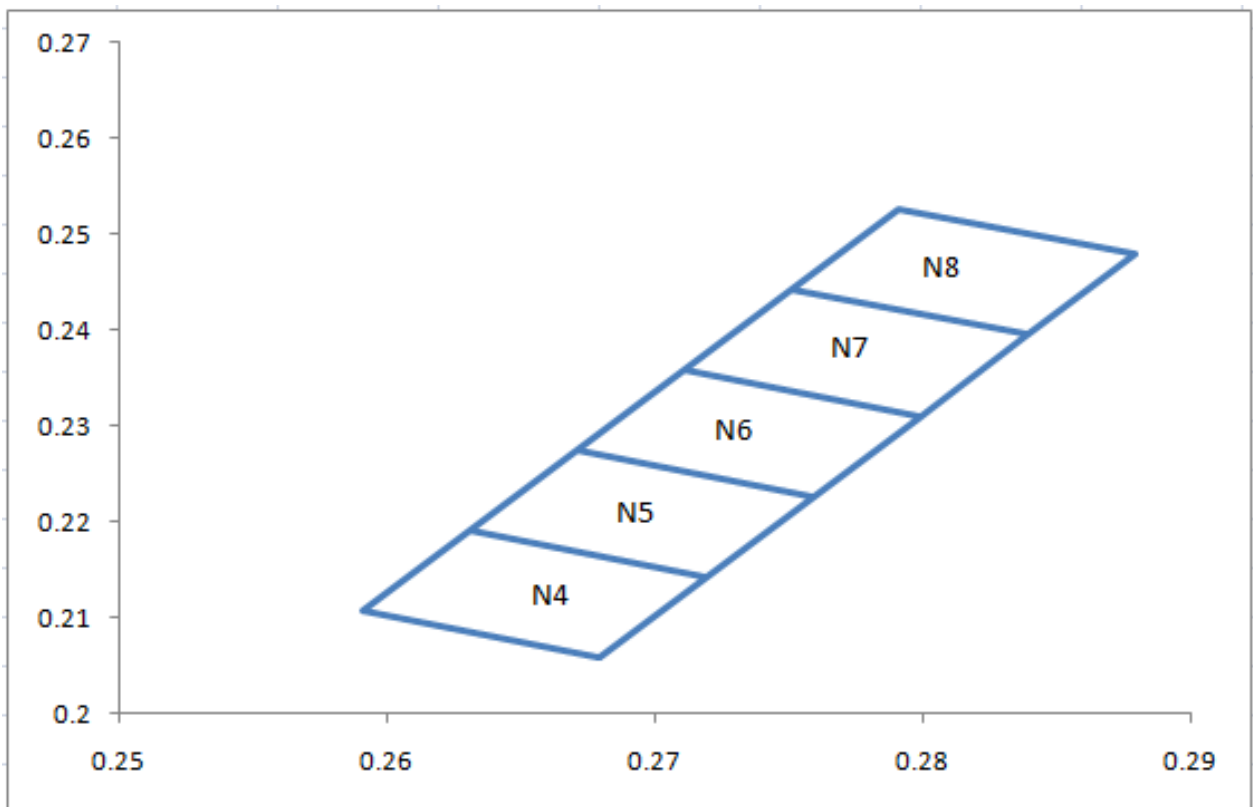
Note:

Tolerance of Forward Voltage: ±0.05V.

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| Bin Code | CIE_x | CIE_y | Bin Code | CIE_x | CIE_y |
|----------|--------|--------|----------|--------|--------|
| N4 | 0.2631 | 0.2191 | N7 | 0.2751 | 0.2443 |
| | 0.2719 | 0.2143 | | 0.2839 | 0.2395 |
| | 0.2679 | 0.2059 | | 0.2799 | 0.2311 |
| | 0.2591 | 0.2107 | | 0.2711 | 0.2359 |
| N5 | 0.2671 | 0.2275 | N8 | 0.2791 | 0.2527 |
| | 0.2759 | 0.2227 | | 0.2879 | 0.2479 |
| | 0.2719 | 0.2143 | | 0.2839 | 0.2395 |
| | 0.2631 | 0.2191 | | 0.2751 | 0.2443 |
| N6 | 0.2711 | 0.2359 | | | |
| | 0.2799 | 0.2311 | | | |
| | 0.2759 | 0.2227 | | | |
| | 0.2671 | 0.2275 | | | |

The C.I.E. 1931 Chromaticity Diagram

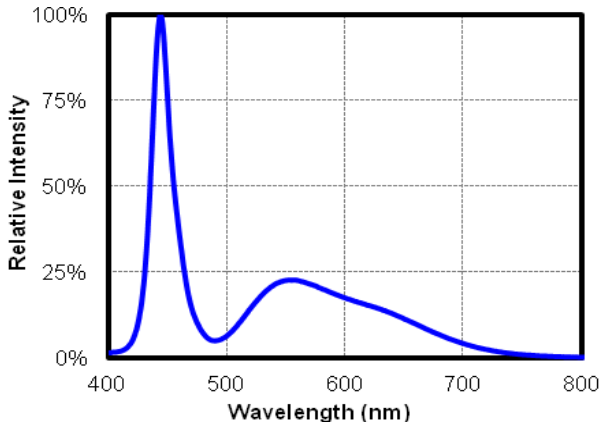


Note:

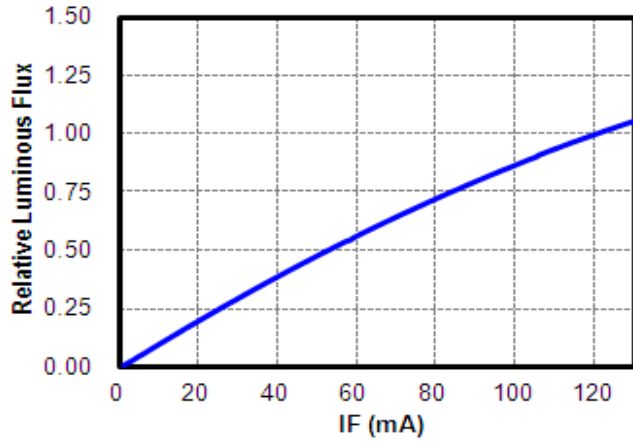
1. The value is based on driving current by 120mA.
2. Tolerance of Chromaticity Coordinates: ± 0.005 .

Typical Electro-Optical-Thermal Characteristics Curves

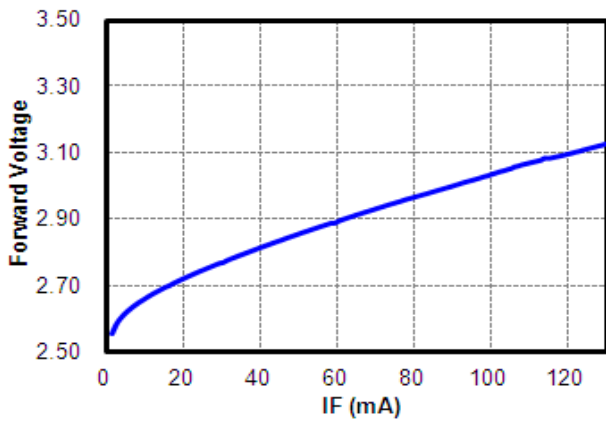
1. Spectrum Distribution
($T_A=25^\circ\text{C}$, $I_F=120\text{mA}$)



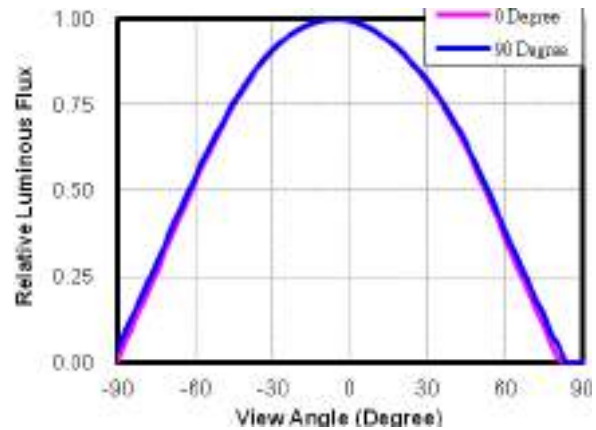
2. Relative Luminous Flux vs. Forward Current
($T_A=25^\circ\text{C}$)



3. Relative Forward Voltage vs. Forward Current
($T_A=25^\circ\text{C}$)

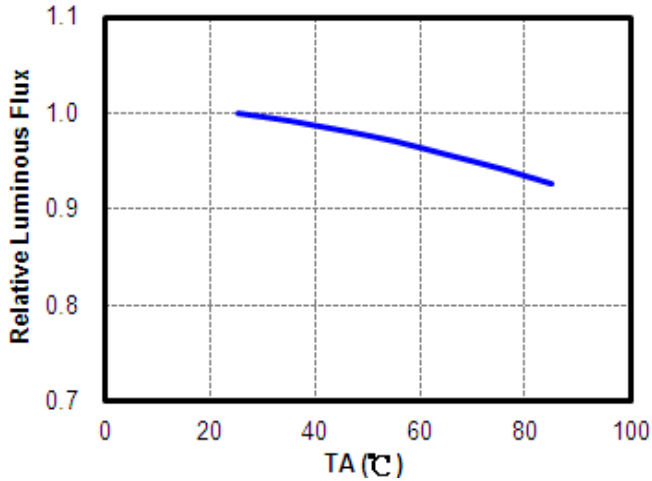


4. Radiation Diagram
($T_A=25^\circ\text{C}$, $I_F=120\text{mA}$)

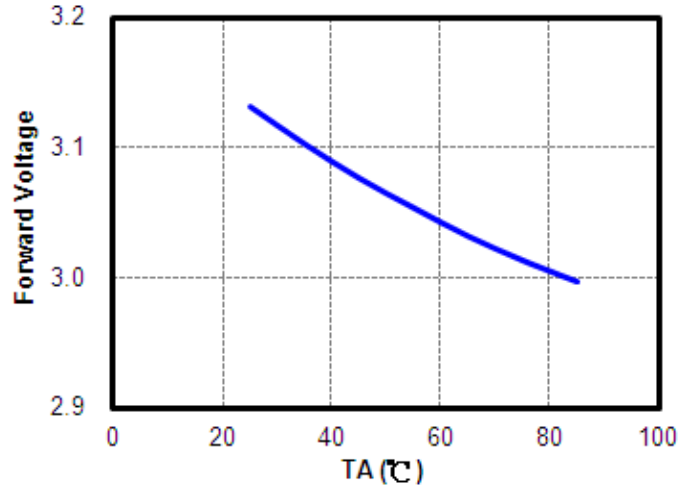


Typical Electro-Optical-Thermal Characteristics Curves

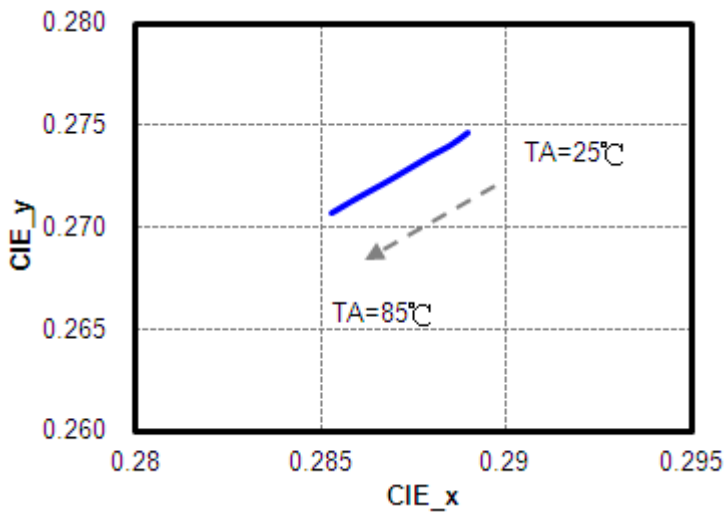
5. Relative Luminous Flux vs. Ambient Temperature
($I_F=120\text{mA}$)



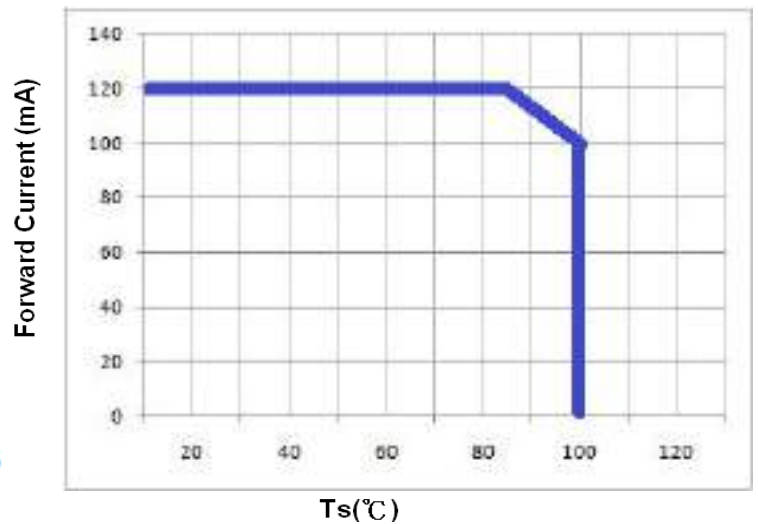
6. Forward Voltage vs. Ambient Temperature
($I_F=120\text{mA}$)



7. Chromaticity Coordinates vs. Ambient Temperature
($I_F=120\text{mA}$)

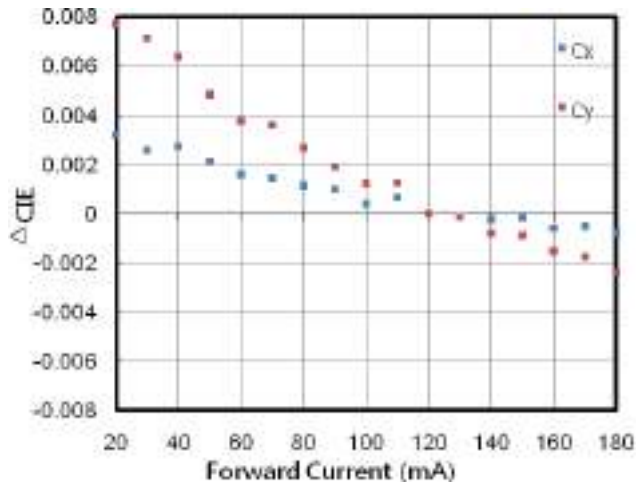


8. Forward Current De-rating Curve

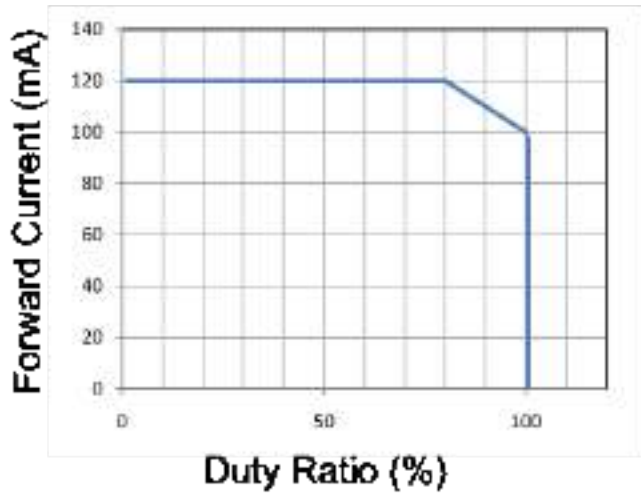


Typical Electro-Optical-Thermal Characteristics Curves

9. Forward current V.S CIE



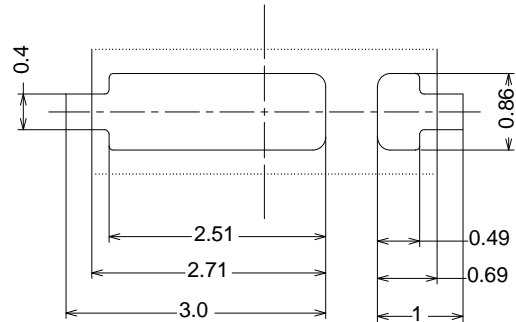
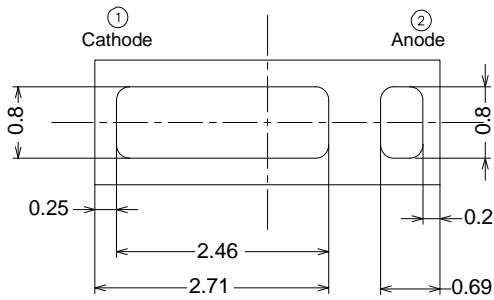
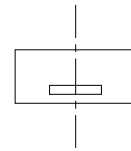
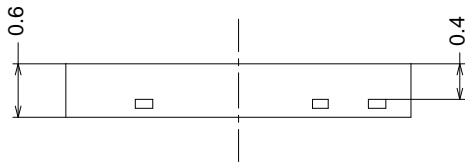
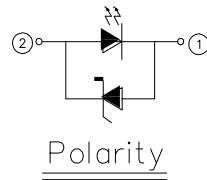
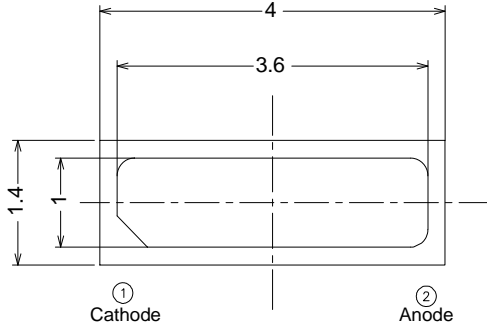
10. Forward Current V.S Duty Ratio



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Package Dimension

4014 (12.6.5)



Bot. view

Soldering pattern

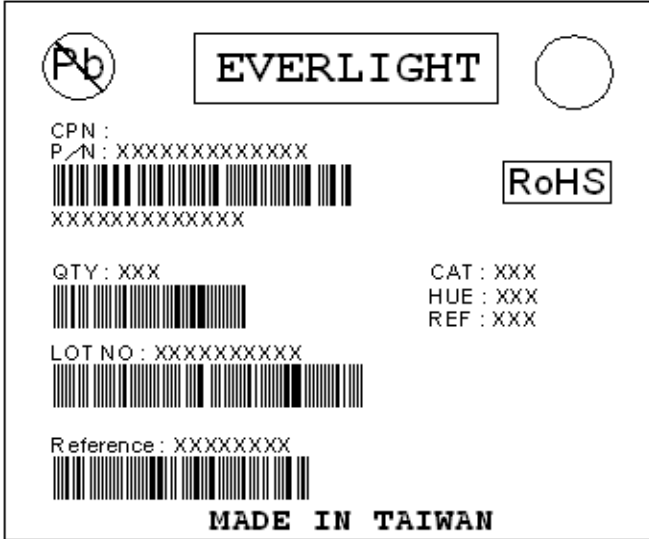
Note:

The tolerance unless mentioned is $\pm 0.1\text{mm}$, unit = mm

50-615TZUMRBC/T2834N489E-T

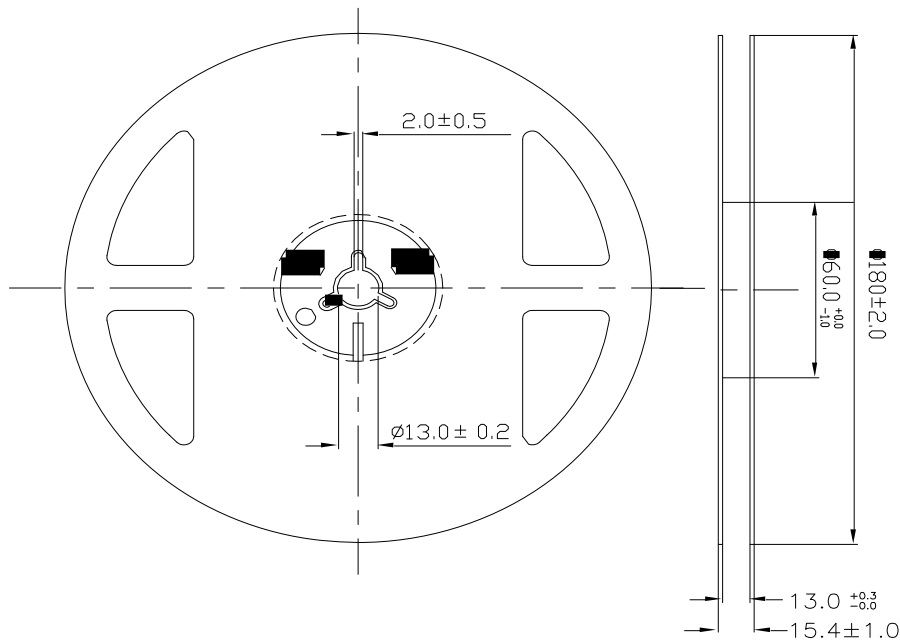
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates
- REF: Forward Voltage Rank
- LOT No: Lot Number

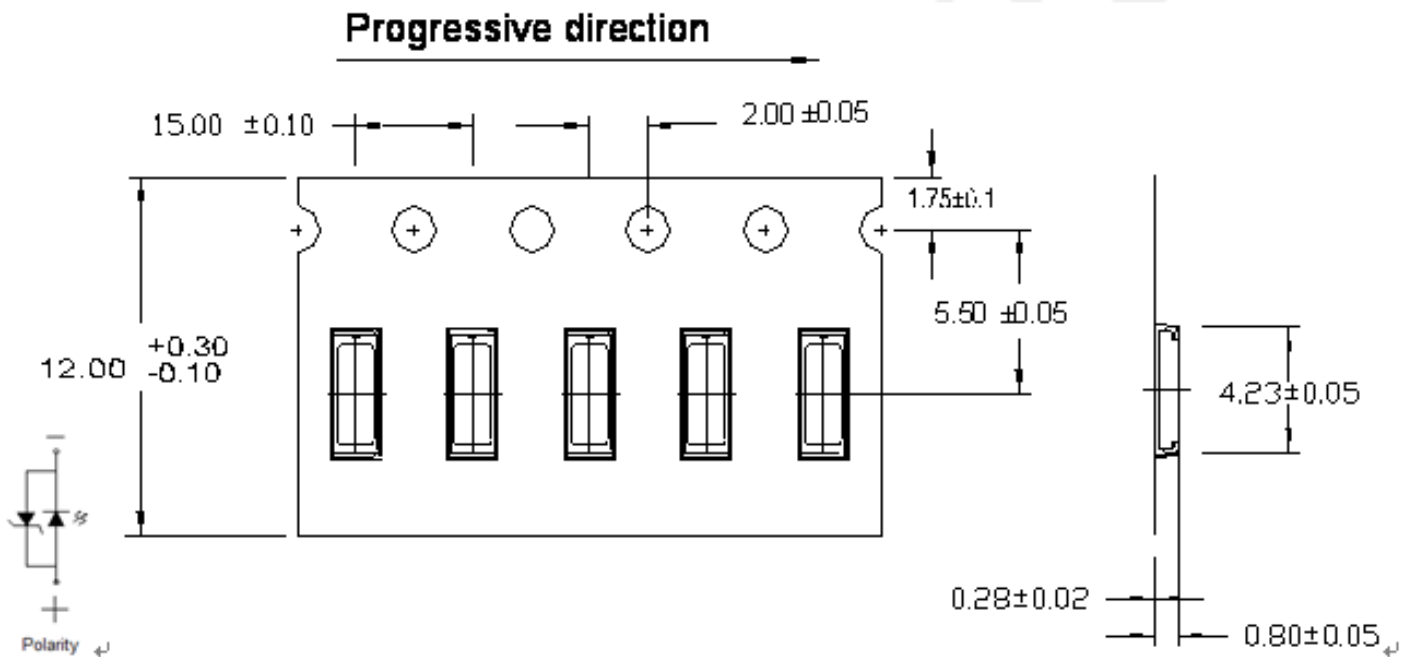
Reel Dimensions



Note:
Tolerances unless mentioned ± 0.1 mm. Unit = mm

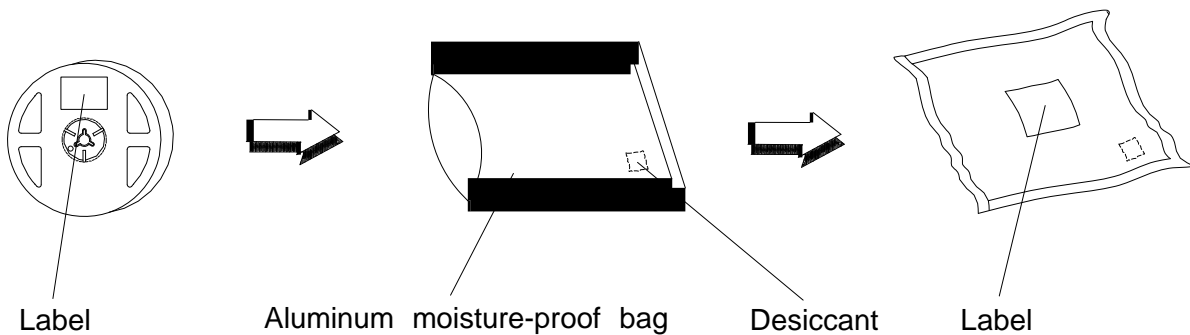
50-615TZUMRBC/T2834N489E-T

Carrier Tape Dimensions: Loaded Quantity 250 up/500/1000/2000 pcs. Per Reel



Note:
Tolerance unless mentioned is ±0.1mm; Unit = mm

Moisture Resistant Packing Process



50-615TZUMRBC/T2834N489E-T

Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level : 90%

LTPD : 10%

| No. | Item | Test Conition | | Test Hours/ Times | Criteria (at std. IF) |
|-----|--|--|---------|----------------------|--------------------------|
| | | Temp./ Humidity | IF (mA) | | |
| 1 | Reflow Soldering | Temp.: 260°C ±5°C Max. 10 sec. | | 2 times | ΔIv < ±15% ΔVF < ±15% |
| 2 | Thermal Cycle | -40°C ~ 100°C 30min. (5min.) 30min. | | 200 cycles | Iv > 70%, VF ±10%, |
| 3 | Thermal Shock | -40°C ~ 100°C 20min. (<15sec.) 20min. | | 200 cycles | |
| 4 | Low Temp. Storage | TA=-40°C | -- | 1000 hrs | |
| 5 | High Temp. Storage | TA=100°C | -- | 1000 hrs | |
| 6 | Temp. Humidity Storage | TA=60°C / 90%RH | -- | 1000 hrs | |
| 7 | Steady State Operating Life of Low Temp. | TA=-40°C | 120 | 1000 hrs | |
| 8 | Steady State Operating Life Condition 1 | TA=25°C / Room Hum. | 120 | 1000 hrs | |
| 9 | Steady State Operating Life Condition 2 | TA=60°C | 120 | 1000 hrs | |
| 10 | Steady State Operating Life of High Temp. | TA=85°C | 60 | 1000 hrs | |
| 11 | Steady State Operating Life of High Humidity Heat | TA=60°C / 90%RH | 120 | 1000 hrs | |

Notes:

1. Sampling for each test item: 22 (pcs.)
2. Test board: MCPCB board thickness=1.6mm, copper layer thickness=0.07mm, $R_{th\ j-a} \cong 50^\circ\text{C}/\text{W}$.
3. Measurements are performed after allowing the LEDs to return to room temperature.

Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be used within one year and kept at 30°C or less and 70%RH or less.

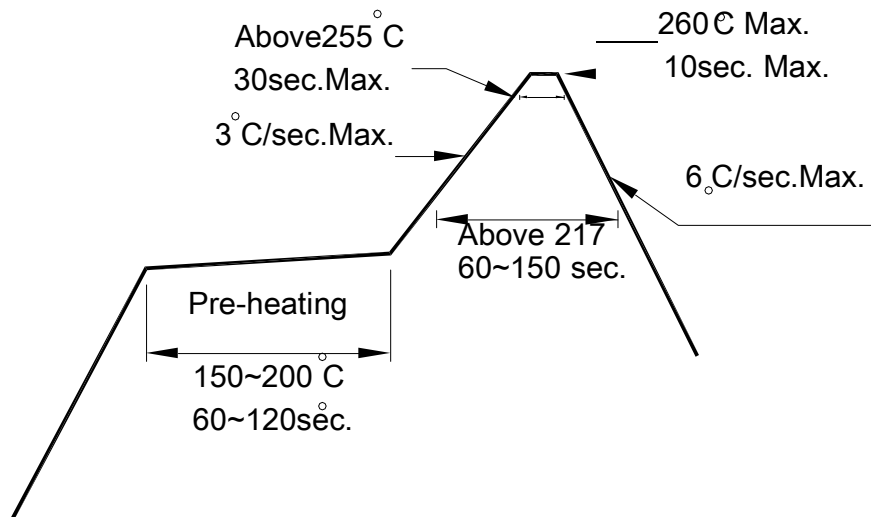
2.3 After opening the package: We recommend that the LED should be soldered quickly (within 3 days). The soldering condition is 30°C or less and 60%RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours. (One time only)

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

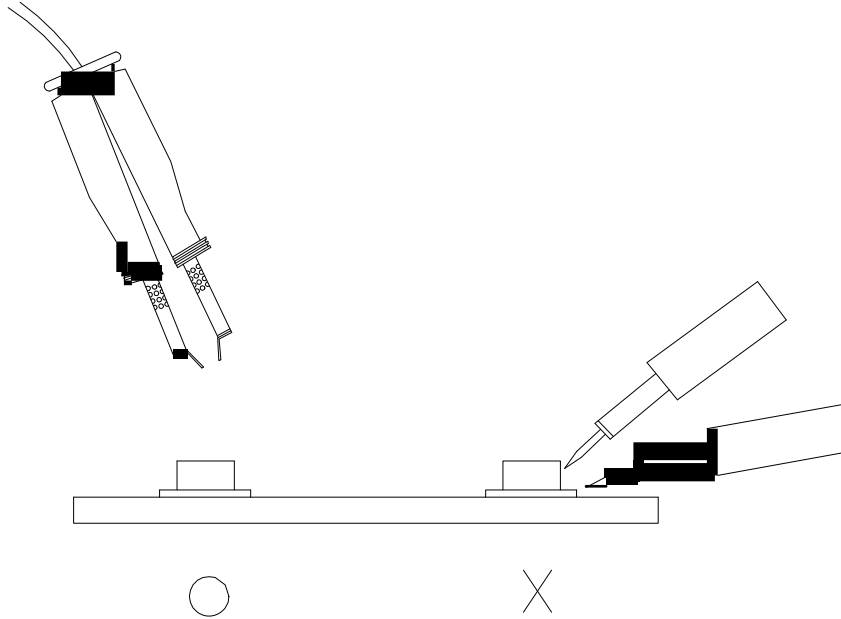
3.4 After soldering, do not warp the circuit board.

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Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6. Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound

EVERLIGHT ELECTRONICS CO., LTD.

Office: No.6-8, Zhonghua Rd.

Tel: 886-2-22685-6688,

Fax: 886-22685-6880,

Shulin Dist., New Taipei City, 23860, Taiwan, R.O.C. <http://www.everlight.com>

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